

ADQ30 Datasheet



The ADQ30 is a high-end 12-bit single-channel data acquisition board optimized for use in high-throughput scientific applications. The ADQ30 features:

- One analog input channel
- 1 GSPS
- 7 GByte/s transfer rate to CPU / GPU / SSD
- Peer-to-peer streaming support
- Two external triggers
- General Purpose Input/Output (GPIO)
- Open FPGA for real-time signal processing

Ordering information

- ADQ30 digitizer including firmware FWDAQ, order code ADQ30.
- ADQ30 digitizer with warranty extension to 5 years, order code ADQ30-W5Y.¹
- Firmware development kit for FWDAQ, order code ADQ30-DEVDAQ.
- Application firmware for averaging FWATD, order code -FWATD.

¹ Included warranty is 3 years from the date the product is shipped by Teledyne SP Devices. The option extends the warranty to 5 years from the date the product is shipped by Teledyne SP Devices. Warranty extension must be ordered before included 3 years warranty is expired.

Datasheet ADQ30 22-2869-A 2023-03-14



1 **ADQ30 INTRODUCTION**

1.1 Features

- One analog input channel •
- 1 GSPS sampling rate •
- 12 bits vertical resolution •
- DC-coupled with 1 GHz bandwidth •
- Programmable DC-offset ٠
- Internal and external clock reference •
- Internal and external sampling clock
- Clock reference output •
- Internal and external triggers •
- 8 GBytes data memory •
- 7 GByte/s data rate to CPU / GPU / SSD •
- Data interface PCIe Gen3 x8 •
- Averaging firmware FWATD •

1.2 **Applications**

- Scientific instruments
- Time-of-flight Mass Spectrometry
- Distributed Optical Fiber Sensing •
- LIDAR •

1.3 Advantages

- A compact high-performance digitizer that optimize the system solution
- Real-time processing and high data throughput •
- Teledyne SP Devices' design services are available for fast integration to reduce time-tomarket

1.4 System design optimization; open FPGA and streaming to CPU and GPU

High-performance data acquisition systems require high speed real-time analysis. ADQ30 offers a variety of options for efficient system design:

Streaming to GPU

ADQ30 supports up to 7 GByte/s peer-to-peer streaming and streaming via pinned buffer to GPU. A GPU offers a powerful platform for implementing application-specific signal processing algorithms.

Streaming to CPU

ADQ30 supports up to 7 GByte/s streaming to host PC. Implementing the application-specific algorithms in the CPU results in a flexible system.

Open FPGA for real-time processing

ADQ30 offers an open FPGA for implementation of the application-specific computations in the FPGA. This gives the most compact system design. Firmware development kit is ordered separately.



2 TECHNICAL DATA

Technical parameters are valid for ADQ30 operating with firmware FWDAQ. All parameters are typical unless otherwise noted.

Table 1 Analog input (front panel label A)

Parameter	Condition	Min	Typical	Max	Unit
Basic parameters					
Number of channels			1		
Sampling rate per channel			1		Gsample/s
Bandwidth	-3dB		1000		MHz
Input range			0.5		Vpp
Input impedance			50		Ω
Coupling			DC		
Connector type		SMA			
Programmable DC-offset		·			
DC-offset range		-0.25		+0.25	V
Dynamic performance		·			
Noise power density	10 to 490 MHz		-144		dBFS/Hz
SNR	0 to 500 MHz, -1dBFS		55		dBc
SFDR	0 to 500 MHz, -1dBFS		64		dBc
ENOB relative full scale	0 to 500 MHz, -1dBFS		8.9		bits
Dynamic performance, FIR fil	lter ²				
SNR	110 MHz, -1dBFS		57		dBc
ENOB relative full scale	110 MHz, -1dBFS		9.4		bits

² Built-in user-programmable digital FIR filter; symmetrical, 17 taps. Filter coefficients used for this test are [57, 92, -279, 21, 704, -720, -1163, 4127, 10784] / 2¹⁴.



Table 2 Clock generator and front panel CLK connector.

Internal clock reference Frequency					
Frequency					
			10		MHz
Accuracy			±3		ppm
			±1/year		
Internal sampling clock gene	erator				
Frequency			1000		MHz
External clock reference inp	ut (from front panel	CLK connect	or) ³		
Frequency		1	10	500	MHz
Frequency ⁴	Jitter cleaner	10	10	500	MHz
	enabled	-10 ppm		+10 ppm	
Frequency	Delay line used		10	100	MHz
Delay line tuning range			500		ps
Signal level		0.5		3.3	Vpp
Input impedance	AC		50		Ω
Input impedance	DC		10k		Ω
Input impedance (high) ⁵	AC		200		Ω
Clock reference output (on f	ront panel CLK conn	ector) ⁶			
Frequency			10		MHz
Signal level	Into 50-Ω load		1.2		Vpp
Output impedance	AC		50		Ω
Output impedance	DC		10k		Ω
External direct sampling clo	ck input (Front pane	I CLK connect	tor) ⁷		
Frequency		1000	1000	1000	MHz
Signal level	Recommended	0.5		3.3	Vpp
Impedance AC			50		Ω
Impedance DC			10k		Ω
Physical connector label CLK	(
Connector type		SMA			

⁵ Software-selectable high-impedance mode.

³ Using a clock reference from an external source to synchronize the ADQ30 to the external source.

 $^{^4}$ The jitter cleaner requires the reference frequency to be a multiple of 10 MHz within \pm 10ppm.

⁶ The internal clock reference of the ADQ30 is made available to synchronize external equipment.

⁷ Use an external clock. Bypass the internal clock generator. The external clock frequency is 5 GHz for

¹⁰ GSPS in 1 channel mode. The external clock frequency is 5 GHz for 5 GSPS in 2 channels mode.



Table 3 Front panel TRIG connector

Parameter	Condition	Min	Typical	Max	Unit
Connector type		SMA			
Used as input (trigger in or GF	0IO)				
Impedance	DC		50		Ω
Impedance (high) ⁸	DC		500		Ω
Signal level	50-Ω mode	-0.5		3.3	V
Adjustable threshold	50-Ω mode	0		2.8	V
Signal level	High impedance	-0.5		5.5	V
Adjustable threshold	High impedance	0		2.3	V
Pulse repetition frequency	As trigger			10	MHz
Time resolution	As trigger		50		ps
Update rate	As GPIO			62.5	MHz
Used as output (trigger out or	GPIO)				
Impedance	DC		50		Ω
Output level high VOH	Into 50-Ω load	1.8			V
Output level low VOL	Into 50-Ω load			0.1	V
Pulse repetition frequency				62.5	MHz

Table 4 Front panel SYNC connector (sync is a trigger signal with limited timing resolution)

Parameter	Condition	Min	Typical	Max	Unit
Connector type		SMA			
Used as input (sync in or GPIC))				
Impedance	DC		50		Ω
Impedance (high) ⁸	DC		500		Ω
Signal range	50-Ω mode	-0.5		3.3	V
Adjustable threshold	50-Ω mode	0		2.8	V
Signal level	High impedance	-0.5		5.5	V
Adjustable threshold	High impedance	0		2.3	V
Pulse repetition frequency	As trigger			10	MHz
Time resolution	As trigger		8		ns
Update rate	As GPIO			62.5	MHz
Used as output (sync out or G	PIO)				
Impedance	DC		50		Ω
Output level high VOH	Into 50-Ω load	1.8			V
Output level low VOL	Into 50-Ω load			0.1	V
Pulse repetition frequency				62.5	MHz

⁸ Software-selectable high-impedance mode.



Table 5 Front panel GPIO connector

Parameter	Condition	Min	Typical	Max	Unit
Connector type		SMA			
Used as input	L.				
Impedance			50		Ω
Impedance (high) ⁸			10		kΩ
Input level high VIH		2			V
Input level low VIL				0.8	V
Update rate				62.5	MHz
Used as output					
Output Impedance			50		Ω
Output level high VOH	Into 50-Ω load	1.5			V
Output level high VOH	No load	3.2			V
Output level low VOL	Into 50-Ω load			0.1	V
Output level low VOL	No load			0.1	V
Update rate				62.5	MHz

Table 6 Custom GPIO expansion. See section 8.

Parameter	Value
Connector type	40-pin FFC/FPC connector, pitch 0.5 mm
Number of differential IO signals LVDS	8
Number of single-ended IO signals 3.3V	5

Table 7 Environment and mechanical parameters

Parameter	Condition	Min	Typical	Max	Unit
Power and temperature					
Power consumption ⁹	FWDAQ		25		W
Power supply		10.8	12	13.2	V
Operating temperature	At fan inlet	0		45	°C
Size			1		
Width			1		slot
Length			225.7		mm
Height			111.2		mm
Compliances	,	·			
RoHS3			Yes		
CE		Yes			
FCC	Exclusion according to CFR 47, part 15, paragraph 15.103(c)			5.103(c)	

⁹ Power consumption depends on firmware option and use case. Power consumption is measured during acquisition and streaming of data at 2 Gbyte/s to PC.



Table 8 Data acquisition

Parameter	Condition	Min	Typical	Max	Unit
Re-arm time				20	ns
Acquisition memory (Data FIFO)	Shared by all channels		8		Gbyte
Record length		16		2 ³¹	samples
Pre-trigger ¹⁰		0		16 360	samples
Length granularity, pre-trigger		8			samples
Trigger delay ¹¹		0		2 ³² -8	samples
Length granularity, trigger delay		8			samples

Table 9 Data transfer

Parameter	Value	Unit
Supported versions of data transfer standard PCIe	Gen1	
	Gen2	
	Gen3	
Supported number of lanes ¹²	1	
	4	
	8	
Data rate sustained	2	GByte/s
Data rate peak	7	GByte/s

Table 10 Software support

Parameter	Value
Operating system ¹³	Windows
	Linux
GUI	Digitizer Studio
Example code	C, Python
API	C / C++

¹⁰ Pre-trigger is set by assigning the parameter "horizontal offset" a negative value

¹¹ Trigger delay is set by assigning the parameter "horizontal offset" a positive value

¹² The ADQ30 must be installed in a 16 lanes slot or a slot with a connector with an open end.

¹³ See 15-1494 Operating system support for a detailed listing of supported distributions

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3 FEATURES FOR DATA FLOW CONTROL, SYNCHRONIZATION AND PROCESSING

The ADQ30 features an advanced machine for flow control, synchronization, and signal processing. The block diagrams are shown in Figure 1 and Figure 2. The features are described in the following tables.

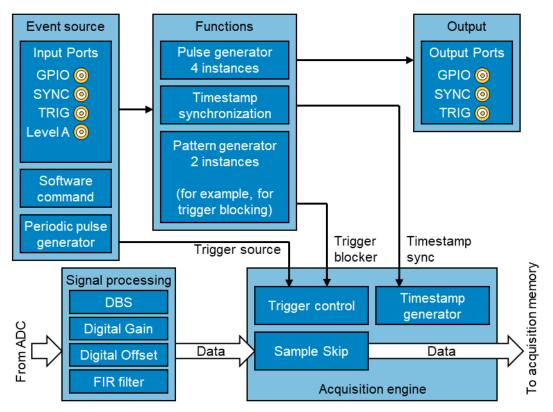


Figure 1 Flow control and synchronization block diagram.

Table 11 Digital signal processing blocks

Object type	Available selections
Digital Signal Processing	Digital Baseline Stabilizer (DBS)
Included signal processing in the data	Digital gain
path for enhanced signal quality.	Digital offset
	Digital FIR filter



Table 12 Flow control blocks

Object type	Available selections
Input ports	Front panel TRIG
Electrical connections to the ADQ30 for	Front panel SYNC
real-time operation (excluding the PCIe	Front panel GPIO
data interface) Used as event source.	Front panel CLK (clock reference or clock input only)
	Analog channel A
Event sources	Software command
Signals for real-time control of activities	External TRIG
in the firmware of ADQ30.	External SYNC
	External GPIO
	Internal periodic event generator
	Level analog channel A
Functions	Pattern generator for timestamp synchronization
Included operations for real-time control	Pattern generator general purpose, 2 instances
of activities in the firmware of ADQ30.	Pulse generator, 4 instances
Output ports	Front panel TRIG
Electrical connections to the ADQ30 for	Front panel SYNC
real-time operation (excluding the PCIe	Front panel GPIO
data interface).	Front panel CLK (clock reference output only)

Table 13 Firmware functions for flow control

Function	Modes/selections	Event sources as stimuli		
Pattern generator for	Software command			
timestamp sync	External TRIG			
Control the time of	External SYNC			
the ADQ30.		Internal periodic event generator		
Pulse generator	Rising edge	Software command		
Control output pulse	Falling edge	External TRIG		
shapes. Three	Pulse length	External SYNC		
instances.	Polarity	Internal periodic event generator		
Pattern generator	Once	Software command		
general purpose	Window	External TRIG		
For example, used for	Gate	External SYNC		
trigger blocking.	Trigger counter	Internal periodic event generator		



Table 14 Firmware functions for acquisition

Function	Modes	Event Sources as stimuli
Trigger		Software command
Initiate the acquisition		External TRIG
of a data record.		External SYNC
		Internal periodic event generator
		Level analog channel A
Data acquisition	Streaming with header	
modes	Streaming without header	
Configurations for		
sending digital data to		
the host PC.		

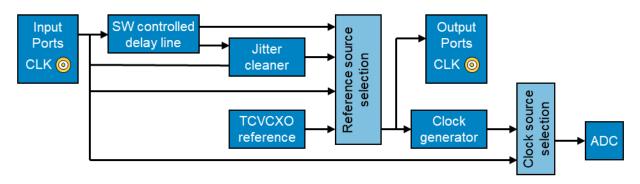


Figure 2 Clock generation block diagram.

Table 15 Clock generation

Function	Modes		
Clock reference source	Internal		
Phase and frequency reference for the	External		
clock system.	External with jitter cleaner and/or delay line		
Sampling clock sources	Internal clock generator		
Actual clock for taking the samples of the	Direct external clock		
analog data.			
Clock output	Selected clock reference		



4 ABSLOUTE MAXIMUM RATINGS

Table 16 Absolute maximum ratings

Parameter	Condition	Min	Max	Unit
Power supply to GND		-0.4	14	V
Operating temperature		0	45	°C
Analog in to GND		-2.5	+2.5	V
TRIG to GND	50-Ω mode	-2	5	V
SYNC to GND	50-Ω mode	-2	5	V
TRIG to GND	500-Ω mode	-2	6	V
SYNC to GND	500-Ω mode	-2	6	V
CLK REF to GND AC amplitude			5	Vpp
CLK REF to GND DC-level		-5	5	V
GPIO to GND		-1.5	5	V
FFC / FPC differential signal to GND	Powered ¹⁴	-0.5	2.3	V
	Not powered ¹⁴	-0.5	0.5	V
FFC / FPC single-ended signal to GND ¹⁴	Powered ¹⁴	-0.3	3.8	V
	Not powered ¹⁴	-0.3	0.5	V

Exposure to conditions exceeding these ratings may reduce lifetime or permanently damage the device. The digitizer with PCIe format has a built-in fan to cool the device. The built-in temperature monitoring unit will protect the digitizer from overheating by temporarily shutting down parts of the device in an overheat situation.

The SMA connectors have an expected lifetime of 500 operations. For frequent connecting and disconnecting of cables, connector savers are recommended.

¹⁴ The absolute maximum ratings depend on whether the ADQ32 is powered or not. It is recommended to use the respective power rail in the FFC connector to power or enable the external drivers to avoid driving overvoltage into an unpowered digitizer. Use the 1.8 V rail for the differential signals and 3.3 V for the single-ended signals.



5 TYPICAL PERFORMANCE

5.1 Frequency response

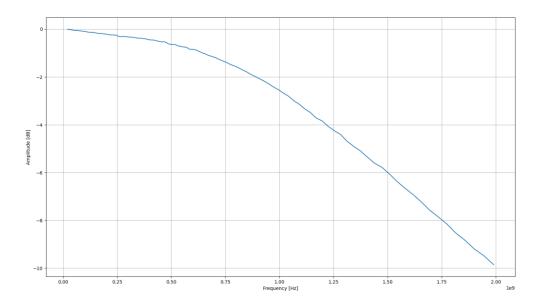


Figure 3 Frequency response, linear frequency scale.

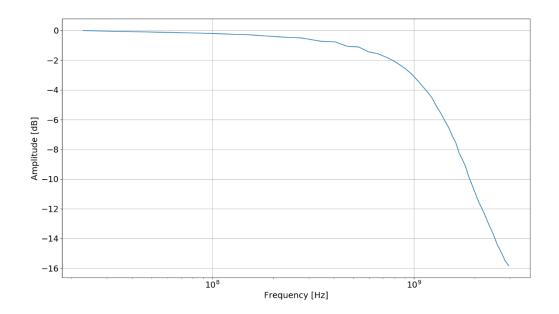


Figure 4 Frequency response, logarithmic frequency scale



5.2 FFT

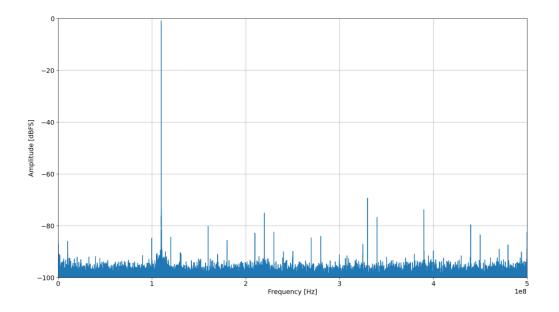


Figure 5 FFT typical performance.

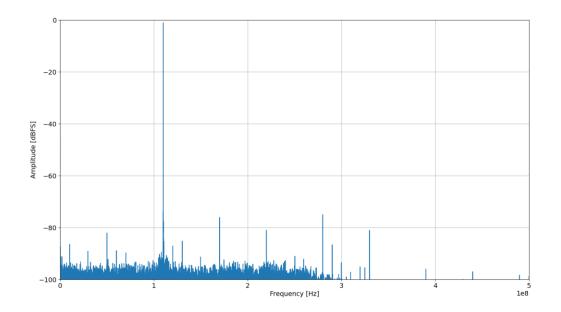


Figure 6 Typical FFT using FIR filter



6 BLOCK DIAGRAM

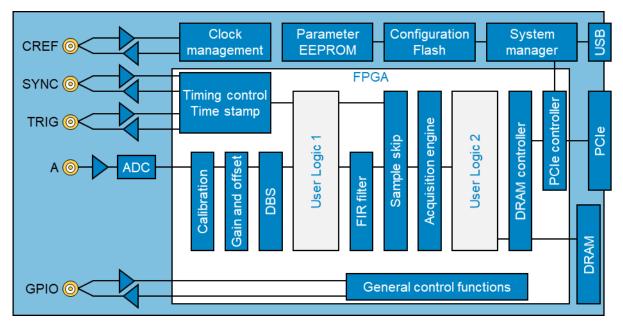


Figure 7 Block diagram.

Figure 7 shows a block diagram of ADQ30. The boxes "User Logic" are open for custom real-signal processing thought the firmware development kit (purchased separately).

7 HOST PC INTERFACE PCIE

The ADQ30-PCIe is powered from the power supply of the PC via a PCI Express 6-pin (2x3) auxiliary power supply connector. The connection in the cable should be as in Figure 8. A suitable connector is for example Molex 45559-0002.

It is important that the auxiliary power supply is turned on immediately when the PC starts. Otherwise, the digitizer will not be recognized on the PCI Express bus.

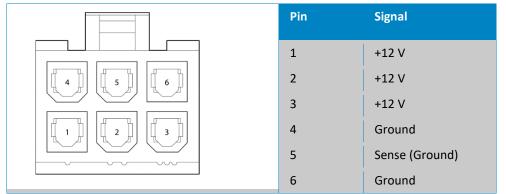


Figure 8 Power supply connection. Cable connector, looking into the connector end.



8 GPIO EXPANSION

The FCP connector allows direct access to the FPGA for building custom expansion boards. The FCP connector requires custom firmware and is accessible through the FPGA development kit. The ADQ32 user guide document number 21-2539 contains a description of connector.

Note that this connector is connected directly to the FPGA. Damage caused by custom hardware failure is not covered by warranty.

Contact Teledyne SP Devices' sales representative for more information.

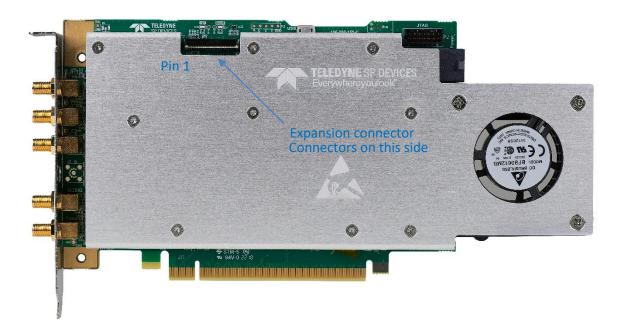


Figure 9 ADQ30 photo showing GPIO expansion connection on the top side.



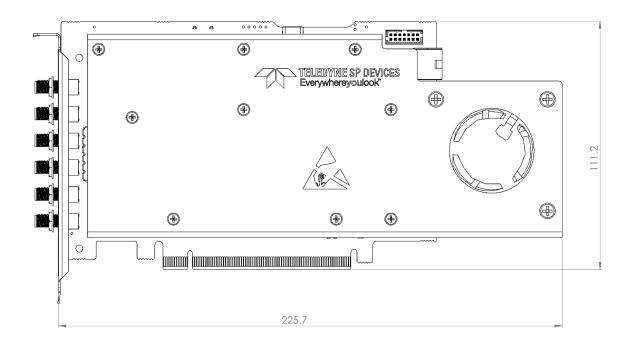


Figure 10 Mechanical drawing (typical)



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